Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP Pavilion dm3 Entertainment PC - dm3-2000 to dm3-2999
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Card reader, SD RAM, motherboard, IO board</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Coin cell battery, Battery pack</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at EL-MF877-01
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner
Include the cartridges, print heads, tubes, vent chambers, and service stations. 0

Components and waste containing asbestos 0

Components, parts and materials containing refractory ceramic fibers 0

Components, parts and materials containing radioactive substances 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screwdriver</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble Main Battery
2. Disassemble Rubber feet*5
3. Dis-fasten BASE screw*5
4. Pull out Keyboard membrane
5. Pull out Touchpad FFC
6. Remove KB Deck
7. Pull out SD board cable
8. Dis-fasten SD board screw*1
9. Remove SD board
10. Pull out WLAN cables
11. Dis-fasten WLAN module screw*1
12. Remove WLAN module
13. Pull out WLAN cables from rubbers & mylar
14. Pull out LCD cable from mainboard
15. Dis-fasten mainboard screw*1
16. Remove Mainbaord
17. Remove RAM module from Mainboard
18. Pull out DC cable
19. Pull out HDD cable
20. Pul out Speaker cable
21. Pull out Thermal module fan cables*2
22. Dis-fasten Thermal module screw*5
23. Remove Thermal module
24. Remove HDD
25. Pull out HDD connector
26. Dis-fasten Speaker screw*2
27. Remove Speaker
28. Dis-fasten DC Bracket screw
29. Remvoe DC Bracket

PSG instructions for this template are available at EL-MF877-01
30. Remove DC Jack
31. Dis-fasten Hinge Block screw*2
32. Remove Hinge-up (LCD module assy)
33. Dis-fasten IO board screw*2
34. Remove IO board
35. Remove Touchpad Bracket Mylar
36. Dis-fasten Touchpad Bracket screw*6
37. Remove Touchpad Bracket
38. Pull out Touchpad FFC
39. Remove Touchpad glass assembly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
B116XW01 V0 Disassembly procedure

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B116XW01 V0 Disassembly Procedure

1. Tear open the tapes
2. Loosen the screws
3. Loosen LED light bar FPC
4. Separate LCD cell and BLU
5. Remove optical films, LGP, frame and white sheet
6. Tear open the tape to get LED light bar out.